1-6450121-9 PRELIMINARY

MULTI-BEAM

TE Internal #: 1-6450121-9

PCB Mount Header, Right Angle, Board-to-Board, 68 Position, 2.54 mm / 5.08 mm [.1 in / .2 in] Centerline, Fully Shrouded, Gold,

Through Hole - Solder

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle
Connector System: Board-to-Board

Number of Positions: **68**Number of Rows: **4**

Features

Electrical Characteristics

Operating Voltage

Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Connector Width	23.62 mm[.93 in]
PCB Thickness (Recommended)	2.11 – 2.62 mm[.083 – .103 in]

60 VDC

Connector Height 14.58 mm[.574 in]

Connector Length 111.13 mm[4.375 in]

Other

Position Locations Omitted	Column 11, 12
Number of Blocked Positions	8
EU ELV Compliance	Compliant

Industry Standards

Glow Wire Rating	High Temperature Part - Not Glow Wire
UL Flammability Rating	UL 94V-0

Usage Conditions

Operating Temperature (Max)	105 °C[221 °F]
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]

Mechanical Attachment



Mating Retention Without	
Mating Alignment Type Polarization	
PCB Mount Retention Without	
PCB Mount Alignment Without	
Connector Mounting Type Board Mount	
Mating Alignment With	
Termination Features	
Termination Post & Tail Length 3.43 mm[.135 in]	
Square Termination Post & Tail Dimension .64 mm[.025 in]	
Termination Method to PCB Through Hole - Solder	
Contact Features	
Contact Underplating Material Nickel	
Carata at Un alarma latin as Matarial Thickness	
Contact Underplating Material Thickness 1.27 µm[50 µin]	
Contact Underplating Material Thickness Contact Size .64mm	
Contact Size .64mm	
Contact Size Contact Mating Area Plating Material Thickness .076 µm[3 µin]	
Contact Size Contact Mating Area Plating Material Thickness .076 µm[3 µin] Mating Square Post Dimension .64 mm[.025 in]	
Contact Size Contact Mating Area Plating Material Thickness .076 µm[3 µin] Mating Square Post Dimension .64 mm[.025 in] Contact Shape & Form Square	
Contact Size.64mmContact Mating Area Plating Material Thickness.076 μm[3 μin]Mating Square Post Dimension.64 mm[.025 in]Contact Shape & FormSquarePCB Contact Termination Area Plating Material Thickness2.54 – 5.08 μm[100 – 200 μin]	
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PCB Mount Orientation	Right Angle
Number of Positions	68
Number of Rows	4
Product Type Features	
Mixed & Hybrid Header	Yes
Connector Shape	Rectangular
PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Body Features

Primary Product Color Black	Primary Product Color	Black	
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Operation/Application

Circuit Application	Power & Signal
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Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Yet Reviewed
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: DEC 2012 (138) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Not Yet Reviewed for halogen content
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous



materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

Compatible Parts



Customers Also Bought





















Documents

PCB Mount Header, Right Angle, Board-to-Board, 68 Position, 2.54 mm / 5.08 mm [.1 in / .2 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder



Product Drawings

English

Product Specifications

MBXL R/A HDR 60S+8P

Application Specification

English